



Kingston® SSD OM8SEP4 Series

Product Specification

V1.0

Jun. 2022

Part Number Information

Kingston Part Number	Capacity	Form Factor	FW Version	Flash IC
OM8SEP4256Q-A0	256GB	M.2 2280	SBI01108	KIOXIA BiCS5 TLC
OM8SEP4512Q-A0	512GB	M.2 2280	SBI00111	KIOXIA BiCS5 TLC
OM8SEP41024Q-A0	1024GB	M.2 2280	SBI00111	KIOXIA BiCS5 TLC

Kingston Digital International Ltd Taiwan Branch

No.1-5, Li-Hsin RD. I, Science Park, Hsin-Chu 30078

Phone(886)3 5641539 • Fax(886)3 5666459

<http://www.kingston.com>

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Revision History

Rev.	Date	Changed Contents
Preliminary	2022.03.11	Fisrt version republished
V1.0	2022.06.22	Add performance and power consumption data.

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1. Introduction

1.1 General Description

The Kingston® SSD OM8SEP4 is designed and built for personal computing machines, providing the mobility, stability, reliability and powerless capability. The Kingston® SSD OM8SEP4 utilizes a PCIe Gen4 x4 interface, Non-Volatile Memory Express protocol and adopt SM2267XT controller, Kioxia NAND Flash. The device comes in M.2 2280-S3-M form factor.

Hard drive replacement - Solid-state drives are the next evolution of PC storage and run faster, quieter and cooler than the aging technology inside hard drives. With no moving parts, SSDs are also more durable and more reliable than hard drives.

For desktops and notebooks - Kingston solid-state drives will make your system more responsive, so it boots quicker, loads applications faster and shuts down faster.

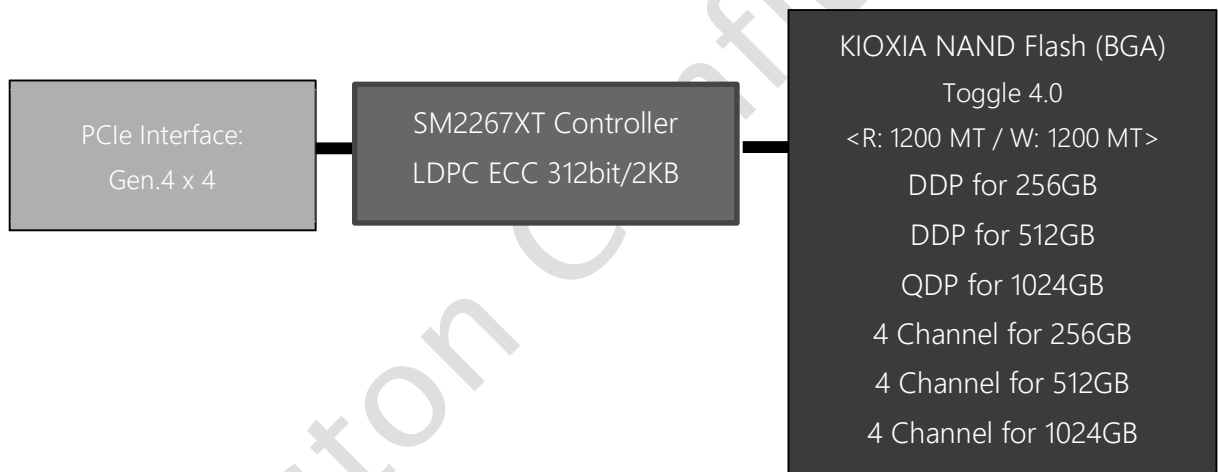


Fig 1-1: Kingston SSD OM8SEP4 Block Diagram

1.2 Advanced Flash Management

1.2.1 Garbage Collection

SSDs incorporate advanced controllers that manage the NAND Flash storage. Kingston® uses *SiliconMotion®*-based controllers in specific SSDs to provide customers with better endurance and performance. These controllers use proprietary technologies to conduct Garbage Collection (GC).

When files are deleted in an Operating System such as Windows, the OS just marks its internal file table indicating that the file is deleted. On hard disk drives (HDDs), the now-invalid data remains there and can be directly overwritten by the system to store new data.

NAND Flash-based devices cannot overwrite data that is already there. They have to go through a Program/Erase cycle; to write to an already used block of data, an SSD controller would first copy all valid data (that which is still in use) and write it to empty pages of a different block, erase all the cells in the current block (both valid and invalid data), and then start writing new data to the newly erased block. This process is called Garbage Collection. Newer OSs also support the TRIM command, whereby the OS notifies the SSD that it has deleted specific files so that the SSD can better manage the GC process to recover that space earlier and prevent saving and moving all that invalid data.

1.2.2 Global Wear-Leveling

Kingston Flash storage devices incorporate controllers utilizing advanced wear-leveling technology, which distributes the number of P/E cycles (program/erase) across the Flash memory evenly. Wear-leveling thus extends the useful life of a drive and help maintain consistent performance levels over the life of the drive.

1.3 Functional Description

Key Feature	Specification
APST	Support
ASPM/PCI-PM	Support
Multiple Submission and Completion Queues	Support (Up to queue depth=64K)
S.M.A.R.T	Support
Trim Command	Support
Modern Standby	Support
TCG Pyrite 2.0	Support
NVMe Revision 1.3	Support
Dynamic & Static Wear-Leveling	Support
Background Garbage Collection	Support
Compatible with PCIe I/II/III/IV x 4 interfaces	Support
Host Memory Buffer	Support
Power Management: (1) PS00 (2) PS01 (3) PS02 (4) PS03 (5) PS04	Support

Table 1-1: Kingston SSD OM8SEP4 Functional Description

2. General Product Specification

2.1 Capacity

Addressable sectors follow the IDEMA organization standard, reference to *Document LBA1-03 LBA Count for Disk Drives Standard*.

Detail information can refer to website: <http://www.idema.org/>

Unformatted Capacity ¹	Total User Addressable Sectors in LBA Mode ²
256GB	500,118,192
512GB	1,000,215,216
1024GB	2,000,409,264

Table 2-1: Kingston SSD OM8SEP4 Capacity Specification

¹ 1 GB = 1,000,000,000 bytes and not all of the memory can be used for storage.

² 1 sector = 512 bytes

2.2 Fundamental Specification

- ◆ Capacity – supporting unformatted capacities¹ of 256GB, 512GB and 1024GB
- ◆ Form-Factor –NGFF-2280, M.2 type
- ◆ Interface – PCIe Gen.4 x4

◆ Performance² –

■ Capacity	256GB	512GB	1024GB
■ Sequential Read	3300 MB/s	3700 MB/s	3700 MB/s
■ Sequential Write	1100 MB/s	2200 MB/s	2680 MB/s
■ 4K Random Read (QD32)	109,000 IOPs	178,000 IOPs	178,000 IOPs
■ 4K Random Write (QD32)	156,000 IOPs	156,000 IOPs	156,000 IOPs

◆ Power consumption³ –

■ Capacity	256GB	512GB	1024GB
■ Maximum Read (Seq.)	2.55 W	2.65 W	2.85 W
■ Maximum Write (Seq.)	4.50 W	5.40 W	6.30 W
■ Avg. consumption	0.25 W	0.26 W	0.27 W

¹ 1 GB = 1,000,000,000 bytes and not all of the memory can be used for storage.

² Performance data reveal the Max. performance consequence, based on CrystalDiskMark 8.0.4

Based on out-of-box performance, speed may have 10% variation due to host hardware, software configuration and usage.

³ Maximum Power bases on IOMeter Read/Write workload. Average bases on MobileMark2018 workload.

2.3 Power Specification

Parameter	Specification
Input Voltage	3.3V +/- 5%
Maximum Ripple	3.3V +/- 10%

Table 2-2: Kingston SSD OM8SEP4 Power Specification

2.4 Endurance Specification

Parameter	Value
Uncorrectable Bit Error Rate(UBER)	Less than 1 sector 10^{15} bits read
Mean Time between Failure(MTBF)	1,500,000 hours

Table 2-3: Kingston SSD OM8SEP4 Endurance Specification

2.5 Warranty Policy

Kingston warrants to the original end user customer that its products are free from defects in material and workmanship. This product is covered by Kingston warranty for one of the following periods, whichever occurs first:

- (i) Three years from the date of purchase by the original end user customer
- (ii) Until the date when the SSD reached its TBW threshold as measured by Kingston software.

Parameter	Specification
Warranty Period	3 years warranty
TBW ¹ (Terabyte Written)	256G – 160 TBW 512G – 320 TBW 1024G – 640 TBW

Table 2-4: Kingston SSD OM8SEP4 Warranty Policy

¹ The value of TBW is calculated by WAF (Write Amplification Factor), which is measured with JEDEC 219A Standard Client Workload.

3. Physical Specification

The M.2 2280 Form-Factor complies with NGFF M.2 SSD standard. Detail mechanical design parameters as below. Tolerance data also included.

Parameter	Specification
Length	80.00mm ± 0.15 mm
Width	22.00mm ± 0.15 mm
Thickness	2.40 mm (max)
Height	1.50 mm (S3) (max)
Weight	8 g (max)

Table 3-1: Mechanical Design Parameters



Figure 3-1: Side View of SSD

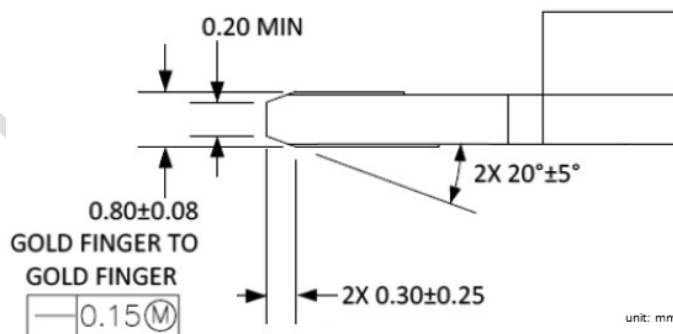
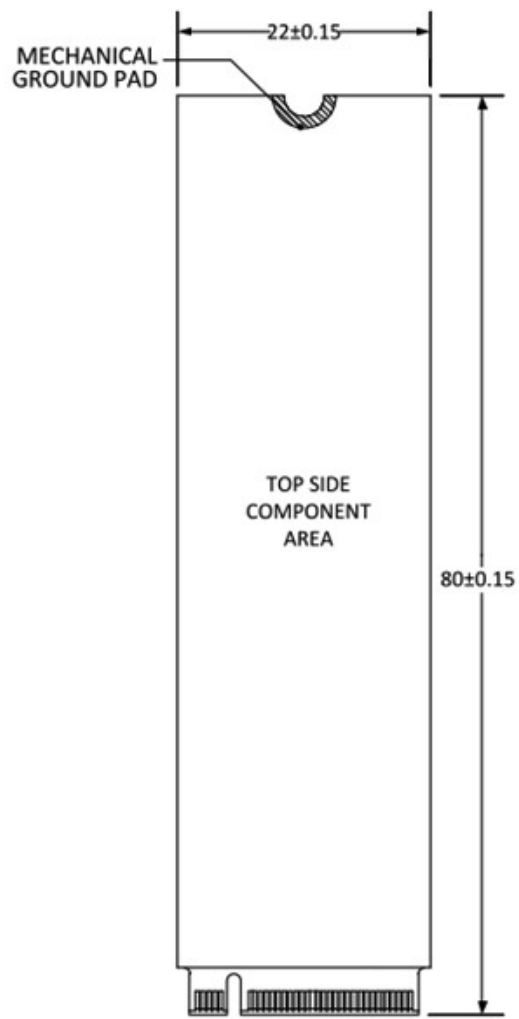
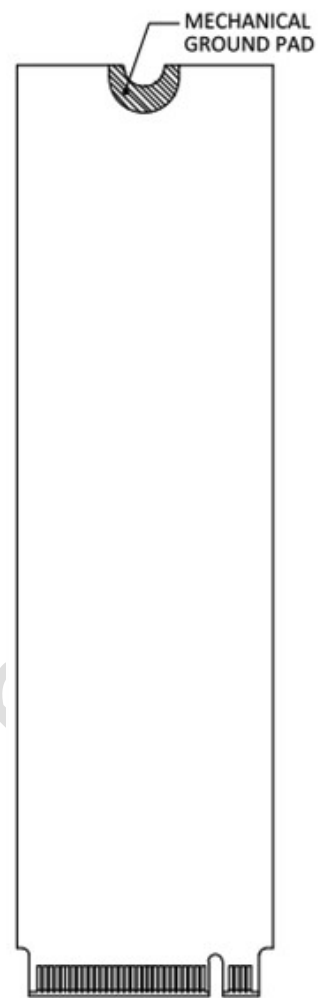


Figure 3-2: Side View of M.2 Connector



unit: mm

Figure 3-3: Top View of SSD



BOTTOM VIEW

Figure 3-4: Bottom View of SSD

4. Environment Specification

4.1 Storage Specification

OM8SEP4 SSD is known as the consumer grade storage product.

Environment	Mode	Min	Max	Unit
Temperature ¹	Operating	0	70	°C
	Storage	-40	85	°C
Humidity	Operating		85	%
	Storage		85	%

Table 4-1: Kingston SSD OM8SEP4 Environment Specification

4.2 Durability Specification

Every material needs to pass the IQC unit's Visual Inspection and quality test. Regular durability test includes the new PCBA and the running material. To make sure product durability is consistence.

Item	Mode	Timing/Frequency	Max
Shock	Operating	@0.5ms/half wave sin	1000G
	Non-operating	@0.5ms/half wave sin	1500G
Vibration	Operating	7-800Hz	2.17G _{rms}
	Non-operating	20-1000Hz	20G _{rms}

Table 4-2: Kingston SSD OM8SEP4 Durability Specification

¹Temperature is measured by sensor, from SMART Attributes.

4.3 Safety Compliance Specification

The Kingston SSD OM8SEP4 is certified to comply with the following standards

Certification	Standard
CE	EN 55032:2015 EN 55024:2010+A1:2015
FCC	FCC 47 CFR Part 15, Subpart B : 2018
Canada	ICES-003 issue 6 2019
RCM	AS/NZS CISPR 32:2015
VCCI	VCCI CISPR 32: 2016
BSMI	CNS 13438 (95 full version) Category B
CB	CB IEC 62368-1, CB IEC 60950-1
EU LVD	EN 62368-1:2014+A11:2017, EN 60950-1:2006+A11:2009+A1:2010+A12:2011 +A2:2013, IEC 62368-1:2014, IEC 60950-1:2005+A1:2009+A2:2013
Other	HF, LF, RoHS, KCC, UKCA
TUV	TUV UL 62368-1, TUV UL 60950-1

Table 4-3: Kingston SSD OM8SEP4 Safety Compliance Specification

5. Pin Definition

Pin #	Type	Description	Pin #	Type	Description
P1	GND	Connect to GND	P31	TXP1	PCIe TX Differential signal
P2	+3.3V AUX1	3.3V Source	P32	N/C	No Connect
P3	GND	Connect to GND	P33	GND	Connect to GND
P4	+3.3V AUX2	3.3V Source	P34	N/C	No Connect
P5	TXN3	PCIe TX Differential signal	P35	RXN1	PCIe RX Differential signal
P6	N/C	No Connect	P36	N/C	No Connect
P7	TXP3	PCIe TX Differential signal	P37	RXP1	PCIe RX Differential signal
P8	PLN	Power Loss Notification	P38	N/C	No Connect
P9	GND	Connect to GND	P39	GND	Connect to GND
P10	DAS	Device Activity Signal	P40	SMB_CLK	SMB_CLK
P11	RXN3	PCIe RX Differential signal	P41	TXN0	PCIe TX Differential signal
P12	+3.3V AUX3	3.3V Source	P42	SMB_DATA	SMB_DATA
P13	RXP3	PCIe RX Differential signal	P43	TXP0	PCIe TX Differential signal
P14	+3.3V AUX4	3.3V Source	P44	ALERT#	ALERT#
P15	GND	Connect to GND	P45	GND	Connect to GND
P16	+3.3V AUX5	3.3V Source	P46	N/C	No Connect
P17	TXN2	PCIe TX Differential signal	P47	RXN0	PCIe RX Differential signal
P18	+3.3V AUX6	3.3V Source	P48	N/C	No Connect
P19	TXP2	PCIe TX Differential signal	P49	RXP0	PCIe RX Differential signal
P20	N/C	No Connect	P50	PERST#	PE-Reset defined by PCIe Mini CEM Spec
P21	GND	Connect to GND	P51	GND	Connect to GND
P22	N/C	No Connect	P52	CLKREQ#	Clock Request defined by PCIe Mini CEM Spec. Used by L1 PM Substates as well.
P23	RXN2	PCIe RX Differential signal	P53	REFCLKN	PCIe reference clock signals
P24	N/C	No Connect	P54	NC	No Connect
P25	RXP2	PCIe RX Differential signal	P55	REFCLKP	PCIe reference clock signals
P26	N/C	No Connect	P56	N/C	No Connect
P27	GND	Connect to GND	P57	GND	Connect to GND
P28	N/C	No Connect	P58	N/C	No Connect
P29	TXN1	PCIe TX Differential signal	P59	Module Key	No Connect
P30	PLA	Power Loss Acknowledge	P60	Module Key	No Connect

P61	Module Key	No Connect	P69	N/C	No Connect
P62	Module Key	No Connect	P70	+3.3V AUX7	3.3V Source
P63	Module Key	No Connect	P71	GND	Connect to GND
P64	Module Key	No Connect	P72	+3.3V AUX8	3.3V Source
P65	Module Key	No Connect	P73	GND	Connect to GND
P66	Module Key	No Connect	P74	+3.3V AUX9	3.3V Source
P67	N/C	No Connect	P75	GND	Connect to GND
P68	N/C	No Connect			

Table 5-1: Pin Assignment

6. Supported NVMe Command List

The Admin Command Set defines the commands that may be submitted to the Admin Submission Queue. Admin commands should not be impacted by the state of I/O queues (e.g., a full I/O completion queue should not delay or stall the Delete I/O Submission Queue command). Table 6-2 defines Admin commands that are specific to the NVM Command Set.

Op Code	Command
00h	Delete I/O Submission Queue
01h	Create I/O Submission Queue
02h	Get Log Page
04h	Delete I/O Completion Queue
05h	Create I/O Completion Queue
06h	Identify
08h	Abort
09h	Set Features
0Ah	Get Features
0Ch	Asynchronous Event Request
10h	Firmware Commit ¹
11h	Firmware Image Download

Table 6-1: Supported Admin Command

Op Code	Command
80h	Format NVM
81h	Security Send
82h	Security Receive

Table 6-2: Supported Admin Command – NVM Command Set Specific

Op Code	Command
00h	Flush
01h	Write
02h	Read
04h	Write Uncorrectable
05h	Compare
08h	Write Zeroes
09h	Dataset Management

Table 6-3: Supported NVM Command

7. Label Definition

Label definition on the label samples (as Fig. 7-1) is only for demonstration of every part on the label, not real information. Detail information is in Table 7-1

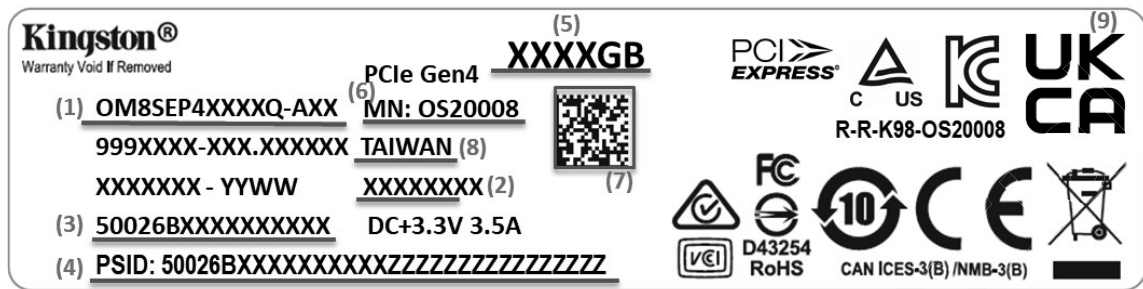


Figure 7-1: Label Sample

No.	Item	Display Sample	Remark
1	SKU	OM8SEP4XXXXQ-AXX	- KTC SKU number (Part number) - xxxx = device capacity (may be 3~4 digits, depending on device capacity)
2	Firmware	256GB: SBI01108 512GB: SBI00111 1024GB: SBI00111	
3	Serial Number	50026BXXXXXXXXXX	Format: 50026BXXXXXXXXXX * XXXXXXXXXXXX : Suffix code
4	PSID	50026BXXXXXXXXXXZZZZZZZZZZZZZZZZ	Format: SN+ZZZZZZZZZZZZZZZZ * ZZZZZZZZZZZZZZZZ: Suffix code
5	Capacity	256GB, 512GB, 1024GB	
6	Series model name	MN: OS20008	
7	2D Barcode	SKU+PSID	2D Barcode
8	Product Made in	TAIWAN / CHINA	
9	Compliance logos		

Table 7-1: Label Information

8. Package Specification

Content Loading definition: 1 Tray = 15 pcs, 1 pizza = 10 Trays = 150pcs SSD

Tray Size: 348 x 188 x 10.8 (mm x mm x mm)

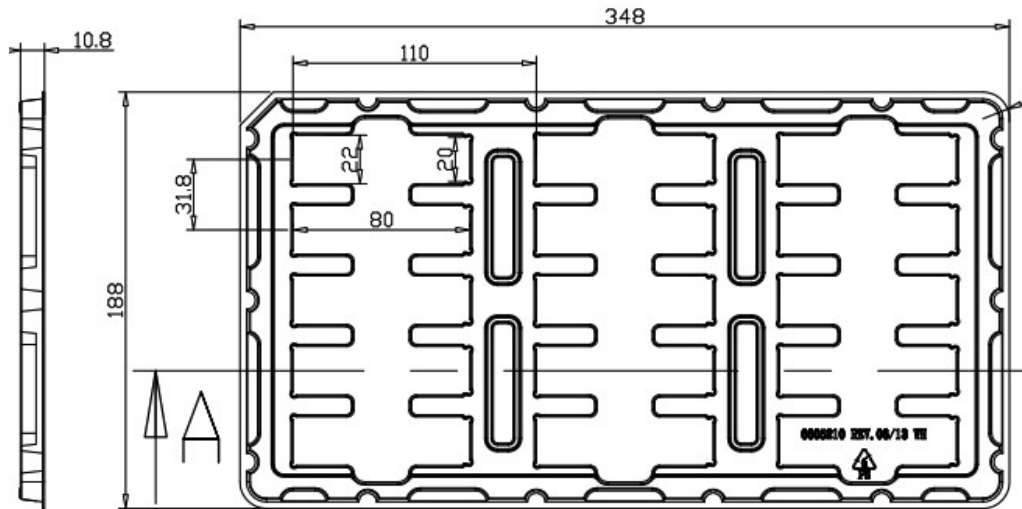


Figure 8-1: Pizza Box

Pizza Box Size: 368 x 205 x 78 (mm x mm x mm)

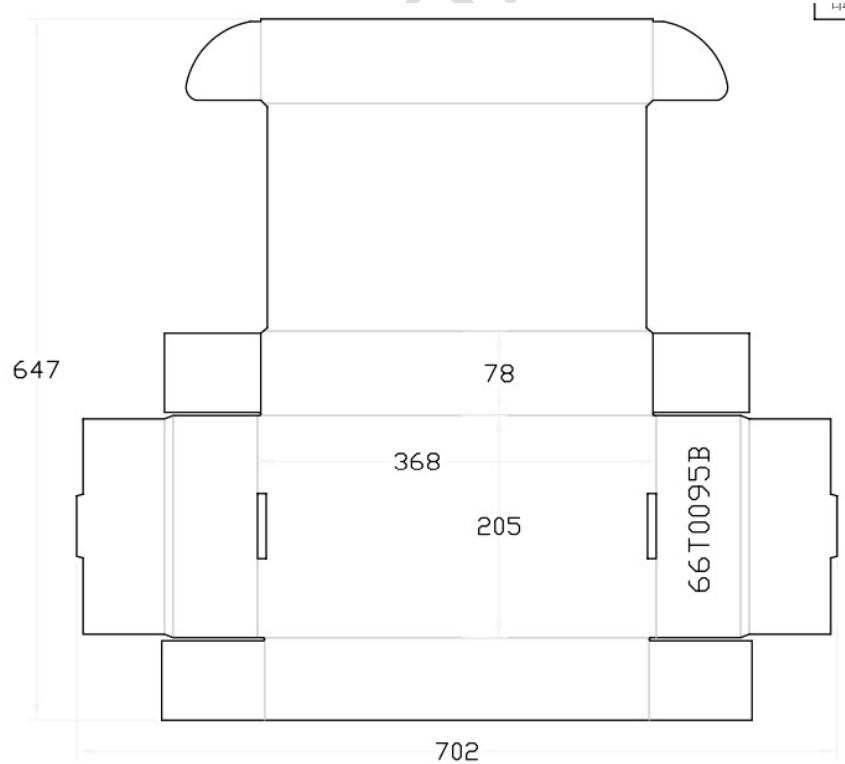


Figure 8-2: Pizza Box

9. SMART Attributes

SMART Attributes provide the SSD's detail working information, like power-on hours or write from host...etc. to help SSD vendor to monitor the health situation and diagnosis while SSD have been damaged or panic under abnormal user behavior.

Attribute Description	Unit
Critical Warning	-
Composite Temperature	K
Available Spare	%
Available Spare Threshold	%
Percentage Used	%
Data Units Read	1000sector
Data Units Written	1000sector
Host Read Commands	Count
Host Write Commands	Count
Controller Busy Time	Count
Power Cycles	Count
Power On Hours	Count
Unsafe Shutdowns	Count
Media and Data Integrity Errors:	Count

Table 9-1: SMART Attribute